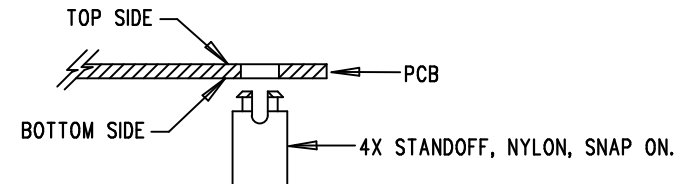


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	DB	07-15-20

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



- 8** SEE THE BILL OF MATERIALS TO MARK THE APPROPRIATE ASSEMBLY TYPE WITH BLACK PERMANENT MARKER. OUTPUT VOLTAGE ON CHANNEL1

A	PROGRAMMABLE
B	FIXED AT 3.3V

APPROVALS

PCB DES.	LT	ANALOG DEVICES POWER BY LINEAR www.analog.com FOR ADI CUSTOMER USE ONLY		
APP ENG.	DB			
		TITLE: TOP ASSEMBLY DRAWING LOW IQ, DUAL, SYNCHRONOUS STEP-DOWN SUPPLY		
		SIZE	IC NO. LTC7802HUFD DC2922A(A,B)	REV. 2
		N/A		
SCALE = NONE		FILENAME: DC2922A-2.PCB		SHT 1 OF 2